## **General Description**

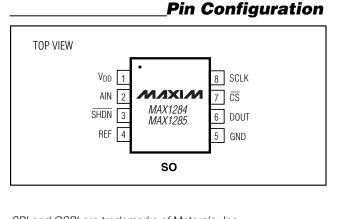
The MAX1284/MAX1285 12-bit analog-to-digital converters (ADCs) combine a high-bandwidth track/hold (T/H), a serial interface with high conversion speed, an internal +2.5V reference, and low power consumption. The MAX1284 operates from a single +4.5V to +5.5V supply. The MAX1285 operates from a single +2.7V to +3.6V supply.

The 3-wire serial interface connects directly to SPI™/QSPI™/ MICROWIRE™ devices without external logic. The devices use an external serial-interface clock to perform successive-approximation analog-to-digital conversions.

Low power, ease of use, and small package size make these converters ideal for remote-sensor and data-acquisition applications or for other circuits with demanding power consumption and space requirements. The MAX1284/MAX1285 are available in 8-pin SO packages.

These devices are pin-compatible, higher-speed versions of the MAX1240/MAX1241. Refer to the respective data sheets for more information.

Applications Portable Data Logging Data Acquisition Medical Instruments **Battery-Powered Instruments** Pen Digitizers **Process Control** 



SPI and QSPI are trademarks of Motorola, Inc. MICROWIRE is a trademark of National Semiconductor Corp.

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For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at 1-888-629-4642. or visit Maxim's website at www.maxim-ic.com.

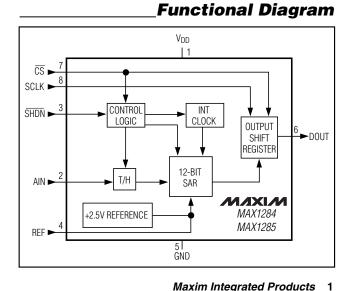
## Features

MXXIM

- Single-Supply Operation +4.5V to +5.5V (MAX1284) +2.7V to +3.6V (MAX1285)
- ±1LSB (max) DNL, ±1LSB (max) INL
- 400ksps Sampling Rate (MAX1284)
- Internal Track/Hold
- +2.5V Internal Reference
- Low Power: 2.5mA (400ksps)
- ♦ SPI/QSPI/MICROWIRE 3-Wire Serial-Interface
- Pin-Compatible, High-Speed Upgrades to MAX1240/MAX1241
- ♦ 8-Pin SO Package

# **Ordering Information**

PART	TEMP. RANGE	PIN- PACKAGE	SUPPLY VOLTAGE (V)
MAX1284BCSA	0°C to +70°C	8 SO	5
MAX1284BESA*	-40°C to +85°C	8 SO	5
MAX1285BCSA	0°C to +70°C	8 SO	2.7 to 3.6
MAX1285BESA	-40°C to +85°C	8 SO	2.7 to 3.6
*Future product—	-contact factory fo	r availabilitv.	



## **ABSOLUTE MAXIMUM RATINGS**

V <sub>DD</sub> to GND -0.3V to +6V   AIN to GND -0.3V to (V <sub>DD</sub> + 0.3V)   REF to GND -0.3V to (V <sub>DD</sub> + 0.3V)   Digital Inputs to GND -0.3V to +6V   DOUT to GND -0.3V to (V <sub>DD</sub> + 0.3V)   POUT to GND -0.3V to (V <sub>DD</sub> + 0.3V)
DOUT Current±25mA
Continuous Power Dissipation (TA = +70°C) 8-Pin SO (derate 5.88mW/°C above +70°C)471mW

Operating Temperature Ranges	
MAX1284BCSA/MAX1285BCSA	0°C to +70°C
MAX1284BESA/MAX1285BESA	40°C to +85°C
Storage Temperature Range	60°C to +150°C
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

# **ELECTRICAL CHARACTERISTICS—MAX1284**

 $(V_{DD} = +4.5V \text{ to } +5.5V; f_{SCLK} = 6.4MHz, 50\% \text{ duty cycle, 16 clocks/conversion cycle (400ksps), 4.7\muF capacitor at REF, T_A = T_{MIN} \text{ to } T_{MAX}$ , unless otherwise noted. Typical values are at T\_A = +25°C.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
DC ACCURACY (Note 1)						
Resolution			12			Bits
Relative Accuracy (Note 2)	INL				±1.0	LSB
Differential Nonlinearity	DNL	No missing codes over temperature			±1.0	LSB
Offset Error					±6.0	LSB
Gain Error (Note 3)					±6.0	LSB
Gain Error Temperature Coefficient				±0.8		ppm/°C
DYNAMIC SPECIFICATIONS (10	0kHz sine wa	ave, 2.5Vp-p, clock = 6.4MHz)	•			•
Signal-to-Noise Plus Distortion Ratio	SINAD			70		dB
Total Harmonic Distortion	THD	Up to the 5th harmonic		-80		dB
Spurious-Free Dynamic Range	SFDR			80		dB
Intermodulation Distortion	IMD	f <sub>IN1</sub> = 99Hz, f <sub>IN2</sub> = 102Hz		76		dB
Full-Power Bandwidth		-3dB point		6		MHz
Full-Linear Bandwidth		SINAD > 68dB		350		kHz
CONVERSION RATE						
Conversion Time (Note 4)	tCONV		2.5			μs
Track/Hold Acquisition Time	tacq				468	ns
Aperture Delay				10		ns
Aperture Jitter				<50		ps
Serial Clock Frequency	<b>t</b> SCLK		0.5		6.4	MHz
Duty Cycle			40		60	%
ANALOG INPUT (AIN)						
Input Voltage Range	VAIN		0		2.5	V
Input Capacitance				18		рF

## ELECTRICAL CHARACTERISTICS—MAX1284 (continued)

 $(V_{DD} = +4.5V \text{ to } +5.5V; f_{SCLK} = 6.4MHz, 50\%$  duty cycle, 16 clocks/conversion cycle (400ksps), 4.7µF capacitor at REF, T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>, unless otherwise noted. Typical values are at T<sub>A</sub> = +25°C.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
INTERNAL REFERENCE						
REF Output Voltage	VREF		2.48	2.50	2.52	V
REF Short-Circuit Current		$T_A = +25^{\circ}C$		30		mA
REF Output Tempco	TC V <sub>REF</sub>			±15		ppm/°C
Load Regulation (Note 5)		0 to 1mA output load		0.1	2.0	mV/mA
Capacitive Bypass at REF			4.7		10	μF
DIGITAL INPUTS (SCLK, CS, SH	DN)					
Input High Voltage	VINH		3.0			V
Input Low Voltage	VINL				0.8	V
Input Hysteresis	V <sub>HYST</sub>			0.2		V
Input Leakage	l <sub>IN</sub>	$V_{IN} = 0 \text{ or } V_{DD}$			±1	μΑ
Input Capacitance	CIN			15		рF
DIGITAL OUTPUT (DOUT)						
Output Voltage Low	Vol	I <sub>SINK</sub> = 5mA			0.4	V
Output Voltage High	VOH	ISOURCE = 1mA	4			V
Three-State Leakage Current	١L	$\overline{\text{CS}} = +5\text{V}$			±10	μA
Three-State Output Capacitance	Соит	$\overline{\text{CS}} = +5\text{V}$		15		рF
POWER SUPPLY						
Positive Supply Voltage (Note 6)	VDD		4.5		5.5	V
Positive Supply Current (Note 7)	IDD	V <sub>DD</sub> = +5.5V		2.5	4.0	mA
Shutdown Supply Current	ISHDN	$SCLK = V_{DD}, \overline{SHDN} = GND$		2	10	μA
Power-Supply Rejection	PSR	$V_{DD} = +5V \pm 10\%$ , midscale input		±0.5	±2.0	mV

## **ELECTRICAL CHARACTERISTICS—MAX1285**

 $(V_{DD} = +2.7V \text{ to } +3.6V; f_{SCLK} = 4.8MHz, 50\% \text{ duty cycle, 16 clocks/conversion cycle (300ksps), 4.7\mu F capacitor at REF, T_A = T_{MIN} \text{ to } T_{MAX}$ , unless otherwise noted. Typical values are at T\_A = +25°C.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
DC ACCURACY (Note 1)						
Resolution			12			Bits
Relative Accuracy (Note 2)	INL				±1.0	LSB
Differential Nonlinearity	DNL	No missing codes over temperature			±1.0	LSB
Offset Error					±6.0	LSB
Gain Error (Note 3)					±6.0	LSB
Gain Error Temperature Coefficient				±1.6		ppm/°C

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# **ELECTRICAL CHARACTERISTICS—MAX1285 (continued)**

 $(V_{DD} = +2.7V \text{ to } +3.0V; f_{SCLK} = 4.8MHz, 50\% \text{ duty cycle, 16 clocks/conversion cycle (300ksps), 4.7\mu F capacitor at REF, T_A = T_{MIN} \text{ to } T_{MAX}$ , unless otherwise noted. Typical values are at T\_A = +25°C.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
<b>DYNAMIC SPECIFICATIONS</b> (75	kHz sine wav	, e, 2.5Vp-p, f <sub>SAMPLE</sub> = 300ksps, f <sub>SCLK</sub> = 4.81	MHz)			
Signal-to-Noise Plus Distortion Ratio	SINAD			70		dB
Total Harmonic Distortion	THD	Up to the 5th harmonic		-80		dB
Spurious-Free Dynamic Range	SFDR			80		dB
Intermodulation Distortion	IMD	$f_{IN1} = 73$ kHz, $f_{IN2} = 77$ kHz		76		dB
Full-Power Bandwidth		-3dB point		3		MHz
Full-Linear Bandwidth		SINAD > 68dB		250		kHz
CONVERSION RATE						
Conversion Time (Note 4)	<b>t</b> CONV		3.3			μs
Track/Hold Acquisition Time	tacq				625	ns
Aperture Delay				10		ns
Aperture Jitter				<50		ps
Serial Clock Frequency	<b>t</b> SCLK		0.5		4.8	MHz
Duty Cycle			40		60	%
ANALOG INPUT (AIN)						
Input Voltage Range	VAIN		0		2.5	V
Input Capacitance				18		рF
INTERNAL REFERENCE						
REF Output Voltage	VREF		2.48	2.50	2.52	V
REF Short-Circuit Current		$T_A = +25^{\circ}C$		15		mA
REF Output Tempco	TC V <sub>REF</sub>			±15		ppm/°C
Load Regulation (Note 5)		0 to 0.75mA output load		0.1	2.0	mV/mA
Capacitive Bypass at REF			4.7		10	μF
DIGITAL INPUTS (SCLK, CS, SH	DN)					
Input High Voltage	VINH		2.0			V
Input Low Voltage	VINL				0.8	V
Input Hysteresis	VHYST			0.2		V
Input Leakage	l <sub>IN</sub>	$V_{IN} = 0 \text{ or } V_{DD}$			±1	μA
Input Capacitance	CIN			15		pF
DIGITAL OUTPUT (DOUT)						
Output Voltage Low	VOL	I <sub>SINK</sub> = 5mA			0.4	V
Output Voltage High	VOH	ISOURCE = 0.5mA	4			V
Three-State Leakage Current	١L	$\overline{\text{CS}} = +3\text{V}$			±10	μA
Three-State Output Capacitance	COUT	$\overline{\text{CS}} = +3\text{V}$		15		pF
POWER SUPPLY						
Positive Supply Voltage (Note 6)	VDD		2.7		3.6	V
Positive Supply Current (Note 7)	IDD	$V_{\text{DD}} = +3.6\text{V}$		2.5	3.5	mA
Shutdown Supply Current	ISHDN	SCLK = V <sub>DD</sub> , SHDN = GND		2	10	μA
Power-Supply Rejection	PSR	$V_{DD}$ = +2.7V to 3.6V, midscale input		±0.5	±2.0	mV

## TIMING CHARACTERISTICS—MAX1284 (Figures 1, 2, 8, 9)

 $(V_{DD} = +4.5V \text{ to } +5.5V, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.})$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
SCLK Period	tCP		156			ns
SCLK Pulse Width High	tсн		62			ns
SCLK Pulse Width Low	tCL		62			ns
CS Fall to SCLK Rise Setup	tcss		35			ns
SCLK Rise to $\overline{CS}$ Rise Hold	tCSH		0			ns
SCLK Rise to $\overline{CS}$ Fall Ignore	tcso		35			ns
CS Rise to SCLK Rise Ignore	tCS1		35			ns
SCLK Rise to DOUT Hold	tdoh	C <sub>LOAD</sub> = 20pF	10			ns
SCLK Rise to DOUT Valid	tDOV	$C_{LOAD} = 20 pF$			80	ns
$\overline{\text{CS}}$ Rise to DOUT Disable	tdod	$C_{LOAD} = 20 pF$	10		65	ns
CS Fall to DOUT Enable	tDOE	$C_{LOAD} = 20 pF$			65	ns
CS Pulse Width High	tcsw		100			ns

# TIMING CHARACTERISTICS—MAX1285 (Figures 1, 2, 8, 9)

( $V_{DD}$  = +2.7V to +3.6V,  $T_A$  =  $T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SCLK Period	tCP		208			ns
SCLK Pulse Width High	tсн		83			ns
SCLK Pulse Width Low	tCL		83			ns
CS Fall to SCLK Rise Setup	tcss		45			ns
SCLK Rise to $\overline{CS}$ Rise Hold	tcsh		0			ns
SCLK Rise to CS Fall Ignore	tcso		45			ns
CS Rise to SCLK Rise Ignore	tCS1		45			ns
SCLK Rise to DOUT Hold	tdoh	C <sub>LOAD</sub> = 20pF	13			ns
SCLK Rise to DOUT Valid	tDOV	$C_{LOAD} = 20 pF$			100	ns
$\overline{\text{CS}}$ Rise to DOUT Disable	tdod	$C_{LOAD} = 20 pF$	13		85	ns
CS Fall to DOUT Enable	tDOE	$C_{LOAD} = 20 pF$			85	ns
CS Pulse Width High	tcsw		100			ns

**Note 1:** Tested at VDD = VDD(MIN).

Note 2: Relative accuracy is the deviation of the analog value at any code from its theoretical value after the full-scale range has been calibrated.

Note 3: Internal reference, offset, and reference errors nulled.

Note 4: Conversion time is defined as the number of clock cycles multiplied by the clock period; clock has 50% duty cycle.

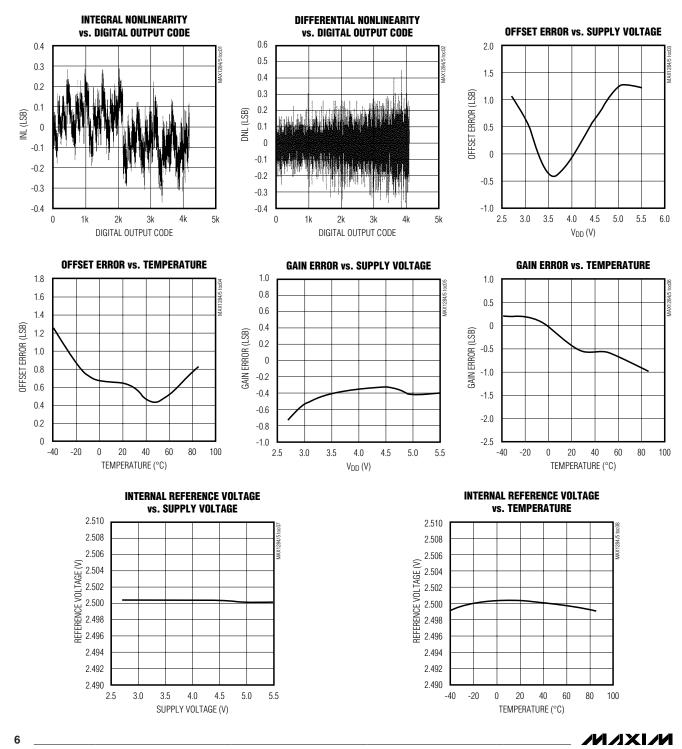
Note 5: External load should not change during conversion for specified accuracy. Guaranteed specification limit of 2mV/mA due to production test limitations.

Note 6: Electrical characteristics are guaranteed from VDD(MIN) to VDD(MAX). For operations beyond this range, see Typical Operating Characteristics.

Note 7: MAX1284 tested with 20pF on DOUT and fSCLK = 6.4MHz, 0 to 5V. MAX1285 tested with same loads, fSCLK = 4.8MHz, 0 to 3V. DOUT = full scale.

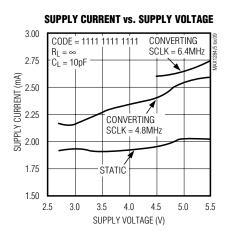
(MAX1284:  $V_{DD}$  = +5.0V,  $f_{SCLK}$  = 6.4MHz, MAX1285:  $V_{DD}$  = +3.0V,  $f_{SCLK}$  = 4.8MHz;  $C_{LOAD}$  = 20pF, 4.7µF capacitor at REF,  $T_A$  = +25°C, unless otherwise noted.)

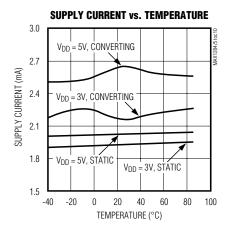
**Typical Operating Characteristics** 



## Typical Operating Characteristics (continued)

(MAX1284: V<sub>DD</sub> = +5.0V,  $f_{SCLK}$  = 6.4MHz, MAX1285: V<sub>DD</sub> = +3.0V,  $f_{SCLK}$  = 4.8MHz; C<sub>LOAD</sub> = 20pF, 4.7µF capacitor at REF, T<sub>A</sub> = +25°C, unless otherwise noted.)





# MAX1284/MAX1285

# **\_Pin Description**

PIN	NAME	FUNCTION
1	VDD	Positive Supply Voltage
2	AIN	Sampling Analog Input, 0 to V <sub>REF</sub> range
3	SHDN	Active-Low Shutdown Input. Pulling $\overline{SHDN}$ low shuts down the device and reduces the supply current to 2 $\mu A$ (typ).
4	REF	Reference Voltage for Analog-to-Digital Conversion. Internal 2.5V reference output. Bypass with 4.7µF capacitor.
5	GND	Analog and Digital Ground
6	DOUT	Serial Data Output DOUT changes state at SCLK's rising edge High impedance when $\overline{\text{CS}}$ is high.
7	CS	Active-Low Chip Select. Initiates conversions on the falling edge. When $\overline{CS}$ is high, DOUT is high impedance.
8	SCLK	Serial Clock Input. SCLK drives the conversion process and clocks data out at rates up to 6.4MHz (MAX1284) or 4.8MHz (MAX1285).

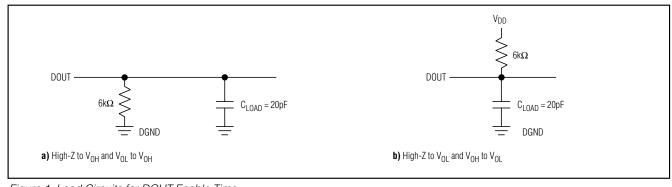


Figure 1. Load Circuits for DOUT Enable Time

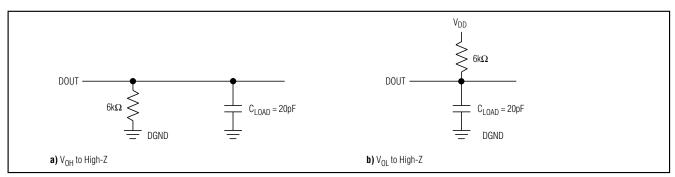


Figure 2. Load Circuits for DOUT Disable Time

# **Detailed Description**

## **Converter Operation**

The MAX1284/MAX1285 use an input T/H and successive-approximation register (SAR) circuitry to convert an analog input signal to a digital 12-bit output. Figure 3 shows the MAX1284/MAX1285 in its simplest configuration. The internal reference is trimmed to +2.5V. The serial interface requires only three digital lines (SCLK,  $\overline{CS}$ , and DOUT) and provides an easy interface to microprocessors (µPs).

The MAX1284/MAX1285 have two modes: normal and shutdown. Pulling SHDN low shuts the device down and reduces supply current to below 2µA (typ), while pulling SHDN high puts the device into operational mode. Pulling CS low initiates a conversion that is driven by SCLK. The conversion result is available at DOUT in unipolar serial format. The serial data stream consists of three zeros, followed by the data bits (MSB first). All transitions on DOUT occur 20ns after the rising edge of SCLK. Figures 8 and 9 show the interface timing information.

Analog Input

Figure 4 illustrates the sampling architecture of the ADC's comparator. The full-scale input voltage is set by the internal reference ( $V_{REF} = +2.5V$ ).

## Track/Hold

In track mode, the analog signal is acquired and stored in the internal hold capacitor. In hold mode, the T/H switch opens and maintains a constant input to the ADC's SAR section.

During acquisition, the analog input (AIN) charges capacitor  $C_{HOLD}$ . Bringing  $\overline{CS}$  low, ends the acquisition interval. At this instant, the T/H switches the input side of  $C_{HOLD}$  to GND. The retained charge on  $C_{HOLD}$  represents a sample of the input, unbalancing node ZERO at the comparator's input.

In hold mode, the capacitive digital-to-analog converter (DAC) adjusts during the remainder of the conversion cycle to restore node ZERO to 0 within the limits of 12bit resolution. This action is equivalent to transferring a charge from  $C_{HOLD}$  to the binary-weighted capacitive DAC, which in turn forms a digital representation of the analog input signal. At the conversion's end, the input

8

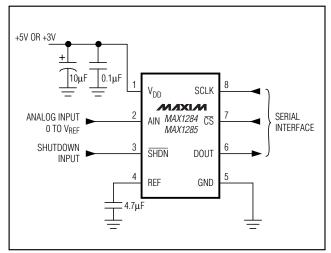


Figure 3. Typical Operating Circuit

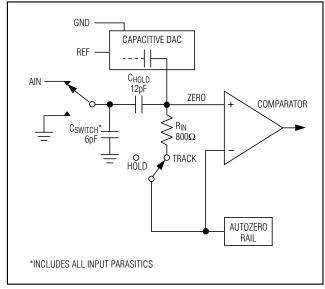


Figure 4. Equivalent Input Circuit

side of  $C_{\text{HOLD}}$  switches back to AIN, and  $C_{\text{HOLD}}$  charges to the input signal again.

The time required for the T/H to acquire an input signal is a function of how quickly its input capacitance is charged. If the input signal's source impedance is high, the acquisition time lengthens and more time must be allowed between conversions. The acquisition time ( $t_{ACQ}$ ) is the maximum time the device takes to acquire the signal, and is also the minimum time needed for the

signal to be acquired. Acquisition time is calculated by:

 $t_{ACQ} = 9(R_S + R_{IN}) \times 12pF$ ,

where R<sub>IN</sub> = 800 $\Omega$ , R<sub>S</sub> = the input signal's source impedance, and t<sub>ACQ</sub> is never less than 468ns (MAX1284) or 625ns (MAX1285). Source impedances below 2k $\Omega$  do not significantly affect the ADCs AC performance.

Higher source impedances can be used if a  $0.01\mu$ F capacitor is connected to the analog input. Note that the input capacitor forms an RC filter with the input source impedance, limiting the ADCs input signal bandwidth.

#### Input Bandwidth

The ADCs' input tracking circuitry has a 6MHz (MAX1284) or 3MHz (MAX1285) small-signal bandwidth, so it is possible to digitize high-speed transient events and measure periodic signals with bandwidths exceeding the ADC's sampling rate, by using undersampling techniques. To avoid aliasing of unwanted high-frequency signals into the frequency band of interest, anti-alias filtering is recommended.

#### Analog Input Protection

Internal protection diodes, which clamp the analog input to V<sub>DD</sub> and GND, allow the input to swing from GND - 0.3V to V<sub>DD</sub> + 0.3V without damage.

# If the analog input exceeds 50mV beyond the supplies, limit the input current to 2mA.

#### Internal Reference

The MAX1284/MAX1285 have an on-chip voltage reference trimmed to 2.5V. The internal reference output is connected to REF and also drives the internal capacitive DAC. The output can be used as a reference voltage source for other components and can source up to  $800\mu$ A. Bypass REF with a  $4.7\mu$ F capacitor. Larger capacitors increase wake-up time when exiting shutdown (see the *Using SHDN to Reduce Supply Current* section). The internal reference is disabled in shutdown (SHDN = 0).

## Serial Interface

#### Initialization after Power-Up and Starting a Conversion

When power is first applied, and if  $\overline{SHDN}$  is not pulled low, it takes the fully discharged  $4.7\mu F$  reference bypass capacitor up to 2ms to provide adequate charge for specified accuracy. No conversions should be performed during this time.

To start a conversion, pull CS low. At CS's falling edge, the T/H enters its hold mode and a conversion is initiated. Data can then be shifted out serially with the external clock.

Using SHDN to Reduce Supply Current Power consumption can be reduced significantly by shutting down the MAX1284/MAX1285 between conversions. Figure 5 shows a plot of average supply current versus conversion rate. The wake-up time (tWAKE) is the time from when SHDN is deasserted to the time when a conversion may be initiated (Figure 6). This time depends on the time in shutdown (Figure 7) because the external 4.7µF reference bypass capacitor loses charge slowly during shutdown and can be as long as 2ms.

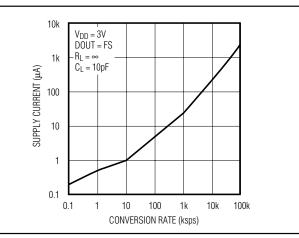


Figure 5. Supply Current vs. Conversion Rate

## **Timing and Control**

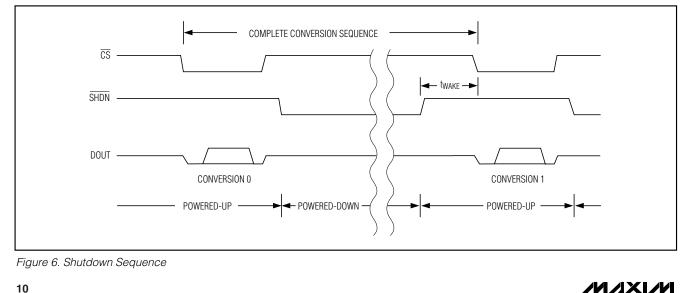
Conversion-start and data-read operations are controlled by the  $\overline{\text{CS}}$  and SCLK digital inputs. The timing diagrams of Figures 8 and 9 outline serial-interface operation.

A  $\overline{CS}$  falling edge initiates a conversion sequence: the T/H stage holds the input voltage, the ADC begins to convert, and DOUT changes from high impedance to logic low. SCLK is used to drive the conversion process, and it shifts data out as each bit of conversion is determined.

SCLK begins shifting out the data after the rising edge of the third SCLK pulse. DOUT transitions 20ns after each SCLK rising edge. The third rising clock edge produces the MSB of the conversion at DOUT, followed by the remaining bits. Since there are twelve data bits and three leading zeros, at least fifteen rising clock edges are needed to shift out these bits. Extra clock pulses occurring after the conversion result has been clocked out, and prior to a rising edge of  $\overline{CS}$ , produce trailing zeros at DOUT and have no effect on converter operation.

Pull  $\overline{CS}$  high after reading the conversion's LSB. For maximum throughout, CS can be pulled low again to initiate the next conversion immediately after the specified minimum time (t<sub>CS</sub>).

**Output Coding and Transfer Function** The data output from the MAX1284/MAX1285 is binary, and Figure 10 depicts the nominal transfer function. Code transitions occur halfway between successiveinteger LSB value  $V_{REF} = +2.5V$ , and  $1LSB = 610\mu V$  or 2.5V/4096.



MAX1284/MAX1285

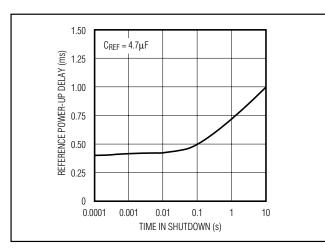


Figure 7. Reference Power-Up vs. Time in Shutdown

# \_Applications Information

## **Connection to Standard Interfaces**

The MAX1284/MAX1285 serial interface is fully compatible with SPI/QSPI and MICROWIRE (Figure 11).

If a serial interface is available, set the CPU's serial interface in master mode so the CPU generates the serial clock. Choose a clock frequency up to 6.4MHz (MAX1284) or 4.8MHz (MAX1285).

- 1) Use a general-purpose I/O line on the CPU to pull  $\overline{\text{CS}}$  low. Keep SCLK low.
- 2) Activate SCLK for a minimum of fifteen clock cycles. The first two clocks produce zeros at DOUT. DOUT output data transitions 20ns after the third SCLK rising edge and is available in MSB-first format. Observe the

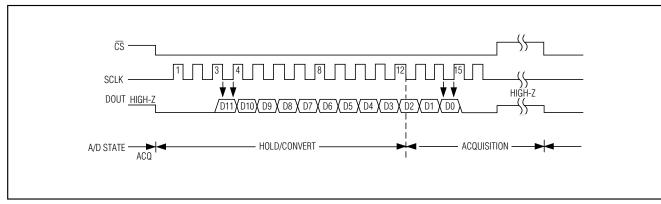


Figure 8. Interface Timing Sequence

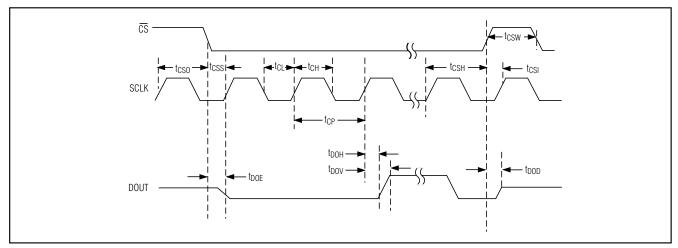


Figure 9. Detailed Serial-Interface Timing

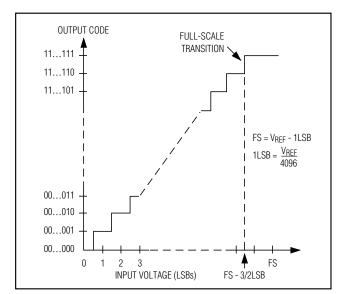


Figure 10. Unipolar Transfer Function, Full Scale (FS) = V<sub>REF</sub> - 1LSB, Zero Scale (ZS) = GND

SCLK to DOUT valid timing characteristic. Data can be clocked into the  $\mu P$  on SCLK rising edge.

- 3) Pull CS high at or after the 15th rising clock edge. If CS remains low, trailing zeros are clocked out after the LSB.
- 4) With CS = high, wait the minimum specified time, t<sub>CS</sub>, before initiating a new conversion by pulling CS low. If a conversion is aborted by pulling CS high before the conversion completes, wait for the minimum acquisition time, t<sub>ACQ</sub>, before starting a new conversion.

CS must be held low until all data bits are clocked out. Data can be output in two bytes or continuously, as shown in Figure 8. The bytes contain the result of the conversion padded with three leading zeros and three trailing zeros.

#### SPI and MICROWIRE

When using SPI or MICROWIRE, set CPOL = 0 and CPHA = 0. Conversion begins with a  $\overline{CS}$  falling edge. DOUT goes low, indicating a conversion in progress. Two consecutive 1-byte reads are required to get the full twelve bits from the ADC. DOUT output data transitions on SCLK's rising edge and is clocked into the following  $\mu$ P on the rising edge.

The first byte contains three leading zeros, and five bits of conversion result. The second byte contains the remaining seven bits and one trailing zero. See Figure 11 for connections and Figure 12 for timing.

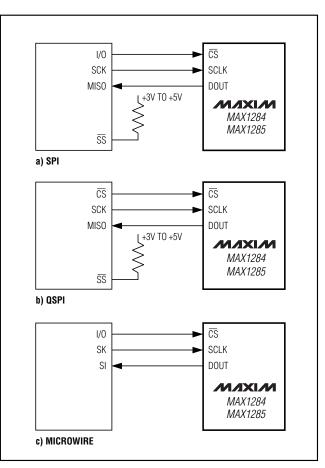


Figure 11. Common Serial-Interface Connections to the MAX1284/MAX1285

#### QSPI

Unlike SPI, which requires two 1-byte reads to acquire the 12 bits of data from the ADC, QSPI allows the minimum number of clock cycles necessary to clock in the data. The MAX1284/MAX1285 require 15 clock cycles from the  $\mu$ P to clock out the 12 bits of data. Figure 13 shows a transfer using CPOL = 0 and CPHA = 1. The conversion result contains two zeros followed by the 12 bits of data in MSB-first formatted.

## Layout, Grounding, and Bypassing

For best performance, use PC boards. Wire-wrap boards are not recommended. Board layout should ensure that digital and analog signal lines are separated from each other. Do not run analog and digital (especially clock) lines parallel to one another, or digital lines underneath the ADC package.

M /X / M

Definitions

## Integral Nonlinearity

Integral nonlinearity (INL) is the deviation of the values on an actual transfer function from a straight line. This straight line can be either a best-straight-line fit or a line drawn between the endpoints of the transfer function, once offset and gain errors have been nullified. The static linearity parameters for the MAX1284/MAX1285 are measured using the endpoints method.

#### **Differential Nonlinearity**

Differential nonlinearity (DNL) is the difference between an actual step width and the ideal value of 1LSB. A DNL error specification of 1LSB or less guarantees no missing codes and a monotonic transfer function.

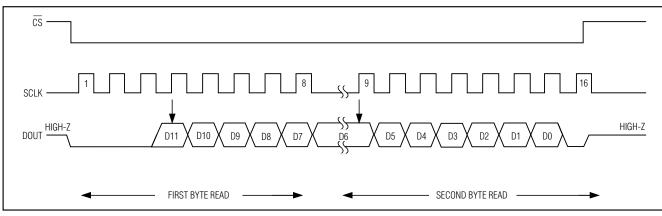


Figure 12. SPI/MICROWIRE Serial Interface Timing (CPOL = CPHA = 0)

Figure 14 shows the recommended system ground con-

nections. Establish a single-point analog ground ("star"

ground point) at GND, separate from the logic ground.

Connect all other analog grounds and DGND to this star

ground point for further noise reduction. No other digital

system ground should be connected to this single-point

analog ground. The ground return to the power supply for

this ground should be low impedance and as short as

High-frequency noise in the V<sub>DD</sub> power supply may affect the ADC's high-speed comparator. Bypass this supply to

the single-point analog ground with 0.1µF and 10µF

bypass capacitors. Minimize capacitor lead lengths for

best supply noise rejection. To reduce the effects of sup-

ply noise, a  $10\Omega$  resistor can be connected as a lowpass

possible for noise-free operation.

filter to attenuate supply noise (Figure 14).

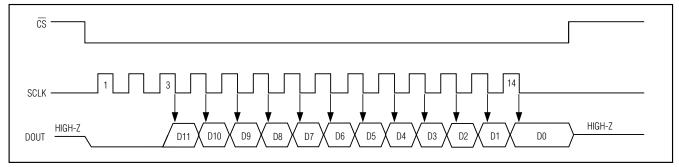


Figure 13. QSPI Serial Interface Timing (CPOL = 0, CPHA = 1)

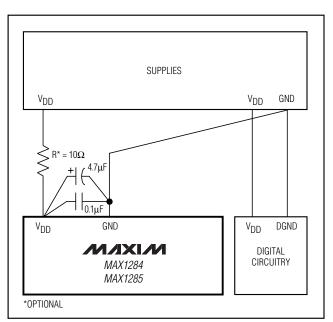


Figure 14. Power-Supply Grounding Condition

#### **Aperture Jitter**

Aperture jitter  $(t_{AJ})$  is the sample-to-sample variation in the time between the samples.

#### **Aperture Delay**

Aperture delay  $(t_{AD})$  is the time defined between the falling edge of  $\overline{CS}$  and the instant when an actual sample is taken.

#### Signal-to-Noise Ratio

For a waveform perfectly reconstructed from digital samples, signal-to-noise ratio (SNR) is the ratio of full-scale analog input (RMS value) to the RMS quantization error (residual error). The theoretical minimum analog-to-digital noise is caused by quantization error, and results directly from the ADC's resolution (N bits):

$$SNR = (6.02 \times N + 1.76) dB$$

In reality, there are other noise sources besides quantization noise, including thermal noise, reference noise, clock jitter, etc. Therefore, SNR is computed by taking the ratio of the RMS signal to the RMS noise, which includes all spectral components minus the fundamental, the first five harmonics, and the DC offset.

#### Signal-to-Noise Plus Distortion

Signal-to-noise plus distortion (SINAD) is the ratio of the fundamental input frequency's RMS amplitude to RMS equivalent of all other ADC output signals.

SINAD (dB) = 20 x log (Signal<sub>RMS</sub>/Noise<sub>RMS</sub>)

#### **Effective Number of Bits**

Effective number of bits (ENOB) indicates the global accuracy of an ADC at a specific input frequency and sampling rate. An ideal ADC's error consists of quantization noise only. With an input range equal to the full-scale range of the ADC, calculate the effective number of bits as follows:

$$\frac{\text{ENOB} = (\text{SINAD} - 1.76)}{6.02}$$

## **Total Harmonic Distortion**

Total harmonic distortion (THD) is the ratio of the RMS sum of the first five harmonics of the input signal to the fundamental itself. This is expressed as:

THD = 20 x log 
$$\left(\frac{\sqrt{V_2^2 + V_3^2 + V_4^2 + V_5^2}}{V_1}\right)$$

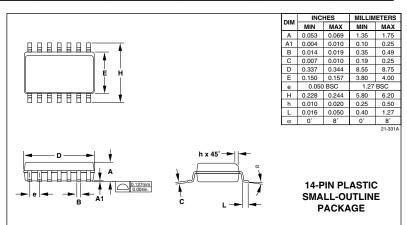
where  $V_1$  is the fundamental amplitude, and  $V_2$  through  $V_5$  are the amplitudes of the 2nd through 5th-order harmonics.

#### **Spurious-Free Dynamic Range**

Spurious-free dynamic range (SFDR) is the ratio of RMS amplitude of the fundamental (maximum signal component) to the RMS value of the next largest distortion component.

## **Chip Information**

TRANSISTOR COUNT: 4286 PROCESS: BICMOS



## **Package Information**

MAX1284/MAX1285

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